

US2016260981A1 ELECTRODEPOSITED COPPER FOIL, AND ELECTRICAL COMPONENT AND BATTERY COMPRISING SAME

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Abstract

Disclosed is an electrodeposited copper foil, in which a center line roughness average Ra (μm), a maximum height Rmax (μm), and a ten-point height average Rz (μm) of a matte side satisfy an Equation below, $1.5 \leq (R_{\text{max}} - R_z) / R_a \leq 6.5$. The electrodeposited copper foil according to the present invention maintains low roughness and high strength, and exhibits a high elongation rate, and particularly, has excellent glossiness, so that the electrodeposited copper foil may be used in a current collector of a medium and large lithigum ion secondary battery and a semiconductor packaging substrate for Tape Automated Bonding (TAB) used in a Tape Carrier Package (TCP).